

Magnetic SMD buzzer

$5 \times 5 \times 3.0 \text{ mm}$

CS05MP030M12-4000

Revision

Date	Version	Status	Changes	Approver
2019/11/13	V0.1	Draft	First release	AX

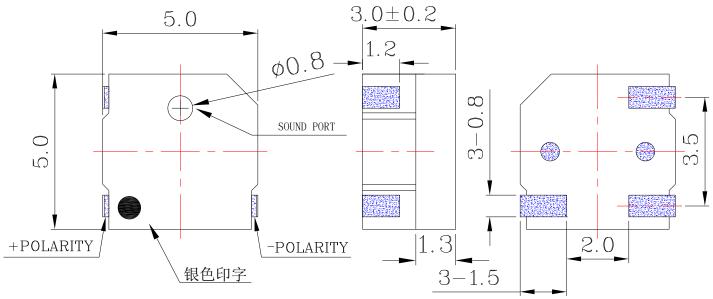
A. SCOPE

This specification applies magnetic buzzer,

B. SPECIFICATION

No.	ltem	Unit	Specification	Condition
1	Oscillation Frequency	Hz	4000	Vo-p=1/2duty , square wave
2	Operating Voltage	Vo-p	2~4	
3	Rated Voltage	Vo-p	3	
4	Current Consumption	mA	MAX.110	at Rated Voltage
5	Sound Pressure Level	dB	MIN. 75	at 10cm at Rated Voltage
6	Coil Resistance	Ω	12±3	
7	Operating Temperature	°C	-20 ~ +60	
8	Storage Temperature	°C	-30 ~ +80	
9	Dimension	mm	5.0 x 5.0 x H3.0	See appearance drawing
10	Weight (MAX)	gram	0.6	
11	Housing Material		LCP(Black)	
12	Leading Pin		Tin Plated Brass(Sn)	See appearance drawing
13	Environmental Protection Regulation		RoHS	

C. APPEARANCE DRAWING



Tol : ± 0.3 Unit: mm

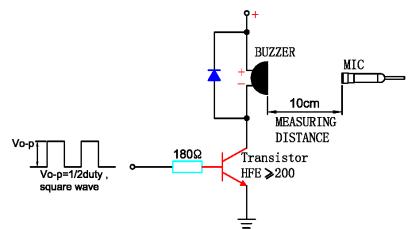
D.TESTING METHOD

Standard Measurement conditions

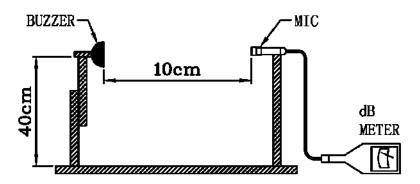
Temperature:25±2°C Humidity:45-65%

Acoustic Characteristics:

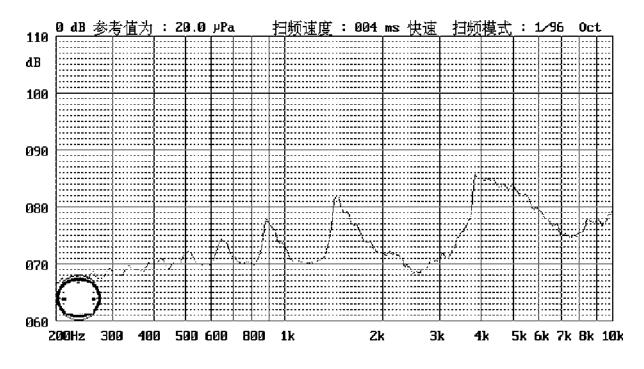
The oscillation frequency, current consumption and sound pressure are measured by the measuring instruments shown below

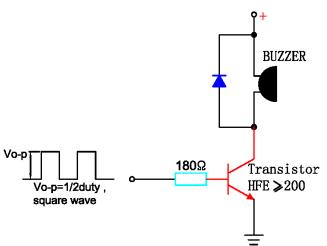


In the measuring test, buzzer is placed as follows:



E. Typical Frequency Response Curve





The base current Ib should high enough so that it saturates the collector current of the transistor with the CB load.

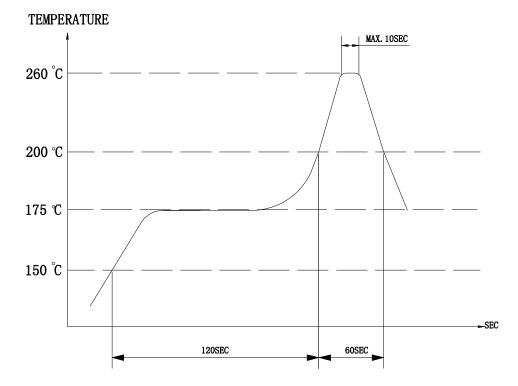
G. Soldering Condition

(1)Recommendable reflow soldering condition is as follows

(Reflow soldering is twice)

Note: It is requested that reflow soldering should be executed

after heat of product goes down to normal.



Heat resistant line

(Used when heat resistant reliability test is performed)

(2)Manual soldering

Manual soldering temperature 350 °C within 5 sec.

H. RELIABILITY TEST

NO.	ITEM	TEST CONDITION AND REQUIREMENT		
	High Temperatura	After being placed in a chamber with 8022°C for 96 hours and then		
1	High Temperature	being placed in normal condition for 2 hours.		
	Test (Storage)	Allowable variation of SPL after test: 10dB.		
	Low Topporatura	After being Placed in a chamber with -302°C for 96 hours and then		
2	Low Temperature Test (Storage)	being placed in normal condition for 2 hours.		
		Allowable variation of SPL after test: 10dB.		
		After being Placed in a chamber with 90-95% R.H. at 40 2°C for 96		
3	Humidity Test	hours and then being placed in normal condition for 2 hours.		
		Allowable variation of SPL after test: 10dB.		
		The part shall be subjected to 5 cycles. One cycle shall be consist of :		
		+60°C		
		+25°C +25°C		
4	Temperature Cycle			
	Test	- 20°C		
		0.5hr 0.5 0.25 0.5 0.5 0.5 0.25		
		3hours		
		Allowable variation of SPL after test: 10dB.		
		Drop on a hard wood board of 4cm thick, any directions ,6 times,		
5	Drop Test	at the height of 75cm.		
	1	Allowable variation of SPL after test: 10dB.		
		After being applied vibration of amplitude of 1.5mm with 10 to 55 Hz		
6	Vibration Test	band of vibration frequency to each of 3 perpendicular directions for		
6	vioration rest	2 hours.		
		Allowable variation of SPL after test: 10dB.		
		Lead terminals are immersed in rosin for 5 seconds and then		
7	Solderability	immersed in solder bath of $+300$ 5°C for 3 1 seconds.		
/	Test	90% min. lead terminals shall be wet with solder		
		(Except the edge of terminals).		
	Tourning! Stuge att	The force of 9.8N(1.0kg) is applied to each terminal in axial direction for		
8	Terminal Strength Pulling Test	10 seconds.		
	i uning iest	No visible damage and cutting off.		

Standard Test Condition	:	a) Temperature : $+5 \sim +35^{\circ}$ C	b) Humidity : 45-85%	c) Pressure : 860-1060mbar
一般测试条件	:	a) 温度 : +5~+35℃	b) 湿度 : 45-85%	c) 气压 : 860-1060mbar
Judgment Test Condition	:	a) Temperature : +25 ± 2°C	b) Humidity : 60-70%	c) Pressure : 860-1060mbar
争议时测试条件	:	a)温度 :+25±2℃	b) 湿度 : 60-70%	c) 气压 : 860-1060mbar

I. PACKING STANDARD

